Notation

T	temperature, K
p	pressure, Pa
v	specific volume, m^3/kg
V_μ	molal volume, $m^3/kmol$
M	molecular mass
c_p	specific isobaric heat capacity, kJ/(kg·K)
c_v	specific isohoric heat capacity, kJ/(kg·K)
λ	thermal conductivity, W/(m·K)
η	viscosity, dynamic, Pa·c
ν	viscosity kinematic, m^2/c
ϱ	density, kg/m^3
ΔH_{vap}	enthalpy change during vaporization (heat of vaporization), kJ/kmol
σ	surface tension, N/m
a	thermal diffusivity, m^2/c
n_D^{20}	refraction index at $T = 293.15$ K
z	compressibility factor
R	gas constant, kJ/(kg·K)
R_μ	universal gas constant
$\tau = T/T_{\text{cr}}$	reduced temperature
$\pi = p/p_{\text{cr}}$	reduced pressure
$\varphi = v/v_{\text{cr}}$	reducer volume
x	property to be found
ω_i	contribution of a chemical structure element to the property to be found
ε	ratio of a number of methyl radicals (CH_3) to a number of phenyl radicals (C_6H_5) in an organosilicon molecule
R_D	mole refraction

Subscripts

liq	liquid
v	vapor
gl	glass transition
cr	critical state
s	saturation
id	ideal-gas state
melt	melting
boil	boiling
vap	vaporization
td	thermal decomposition